Hewlett Packard
Enterprise

Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
JL075A Aruba 3810M 16SFP+ 2-slot Swch

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		1
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		

Item Description	Notes	Quantity of items included in product
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Screw Drivers	T-10
Phillips Screw Driver	

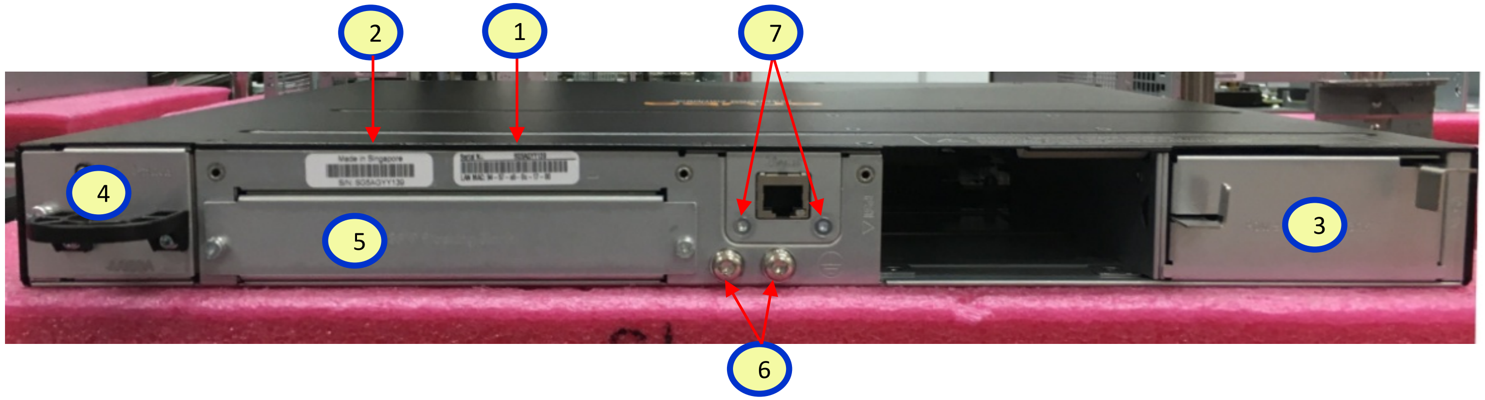
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. 1. See 3.2 for pictorial disassembly instruction. Please open the attachment and print out if needed.
2.
3.
4.
5.
6.
7.
8.

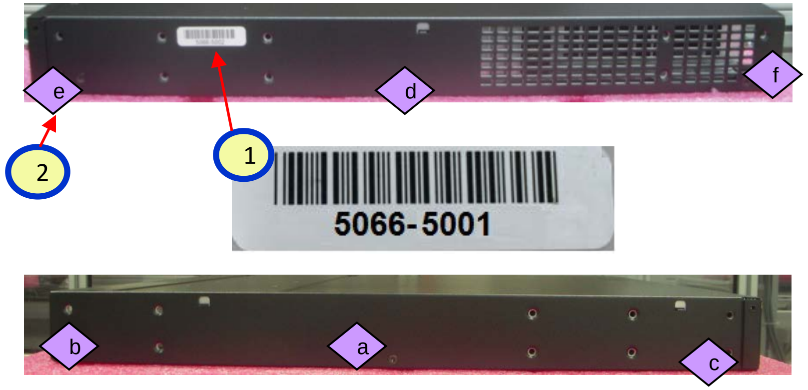
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

JL075A Disassembly Instruction.pptx



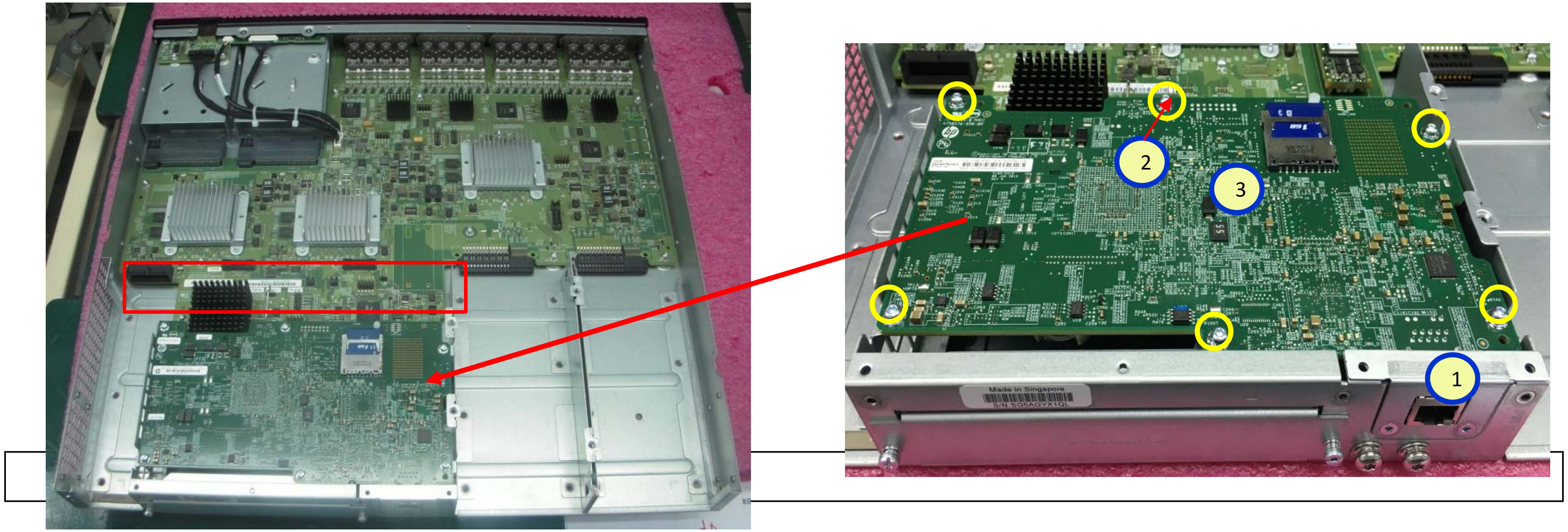
Find	Steps	Description	Quantity
1	Remove	Mac address label	1
2	Un-install	Chassis serial number label	1
3	Un-install	PS Blank Filler	1
4	Unscrew and un-install	Assy, Fan Module, 3810 Switch	1
5	Unscrew and un-install	Assy, Module blank module	1
6	Unscrew and remove	SCREW-MACHINE ASSEMBLY M5 X 0.8 10M ROHS	2
7	Unscrew and remove	SCREW-THD-RLG M3 X 0.5 6MM-LG ROHS	2

○ **Screws must tighten**



Find	Steps	Description	Quantity
1	Remove	Bar Code Label, JL075A	1
2	Un-screw	SCREW-THD-RLG M3 X 0.5	18
3	Remove	Assy, Cover 3810 Non-POE Switch	1

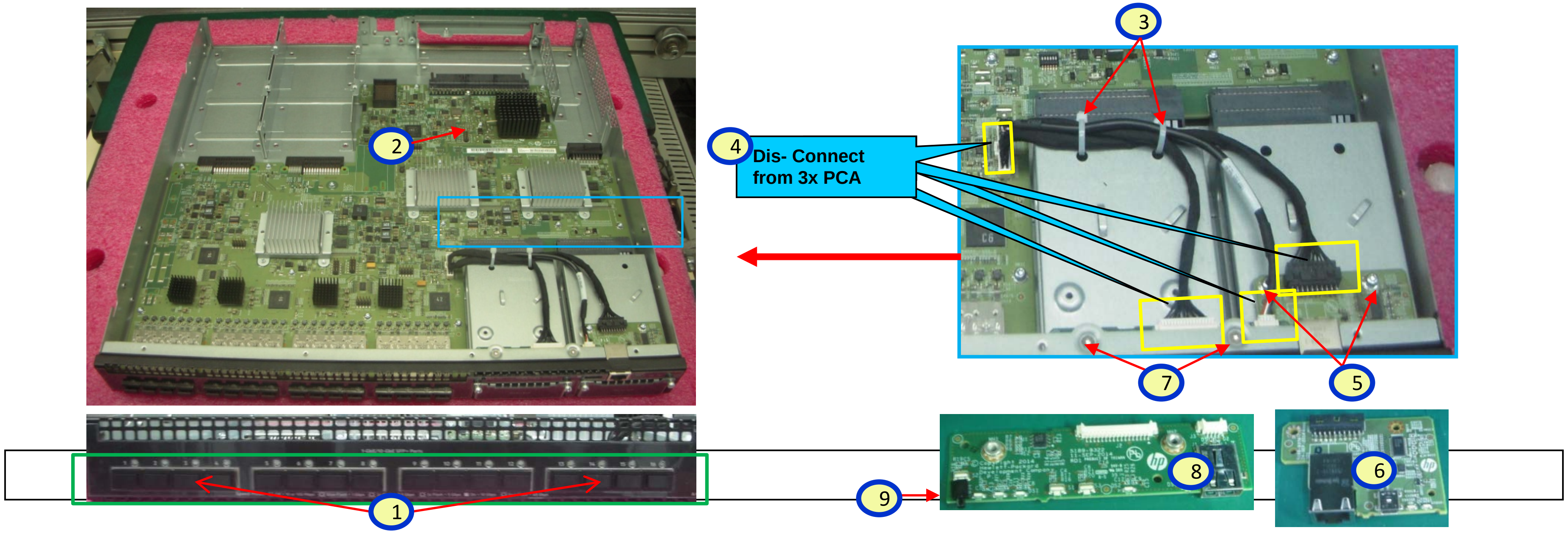
a Follow Sequence.



Find	Steps	Description	Quantity
1	Un-install	COVER, RJ45 CONNECTOR 3810 Switch	1
2	Unscrew	SCREW-MACHINE M3X0.5 6M	6
3	Un-install	Assy, CPU Module w Mech (Wolfgang CPU)	1

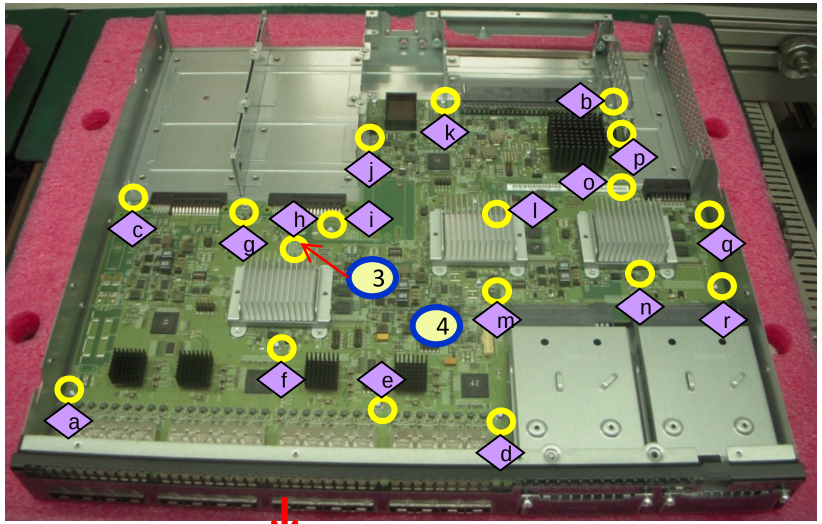
a Follow Sequence.

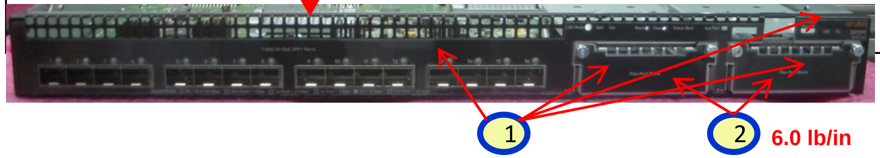
◯ **Screws must tighten**

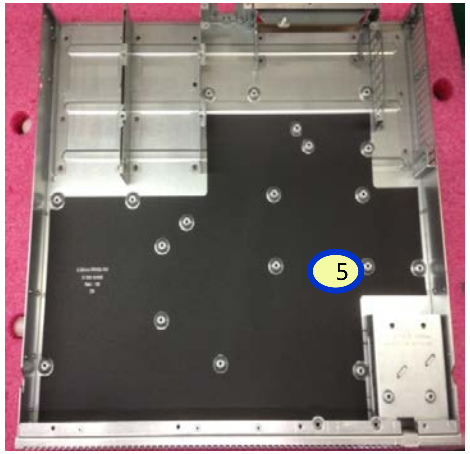


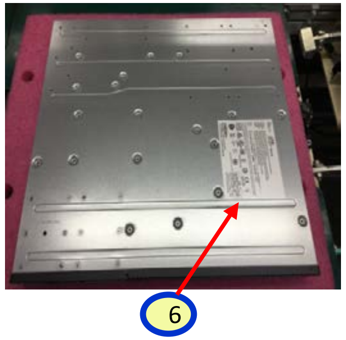
Dis- Connect from 3x PCA

Find	Steps	Description	Quantity
1	Un-install	SFP+ dust cover	16
2	Unscrew	Stdoff Hex Female Stdoff M3-0.5x28mm CS Wz	1
3	Cut	CABLE TIE .062-1.25-DIA .1-WD NYL ROHS	2
4	Disconnect form the 3 x PCA	Wire Harness, 3810 Usability	1
5	Unscrew	SCREW-MACHINE M3X0.5 6M	2
6	Un-install	PCA, Usability_Management	1
7	Unscrew	Screw FH, M3x0.5mm, 6mmL, machine	2
8	Uninstall	PCA, Usability board (Spectre)	1
9	Uninstall	Pushbutton, SMT, Mode Switch	1









Find	Steps	Description	Quantity
1	remove	HP 3810 16 SFP+ Composite Label	1
2	Unscrew and Uninstall	Assy, Bulkhead Blank FP	2
3	Unscrew	SCREW-TAPPING M3 X 0.5	18
4	Un-install	Assy, 16x10GSFP+ w Mech (Icarus)	1
5	Remove	INSULATOR, CHASSIS BASE 3810 SWITCH	1
6	Remove	Lbl, Regulatory JL075A	1